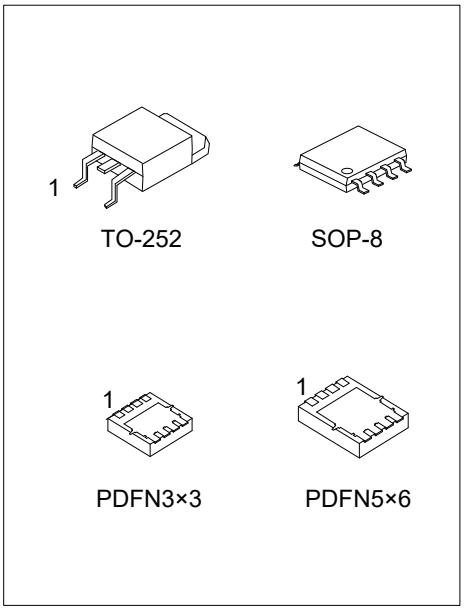
UT25N10

Power MOSFET

25A, 100V N-CHANNEL POWER MOSFET



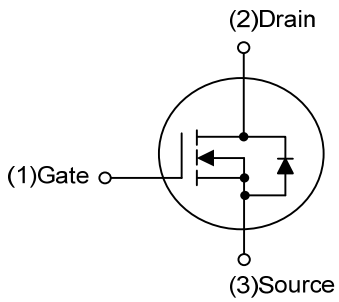
■ DESCRIPTION

The UTC **UT25N10** is a N-channel power MOSFET providing very low on-resistance. It has high efficiency and perfect cost-effectiveness. It can be generally applied in the commercial and industrial fields.

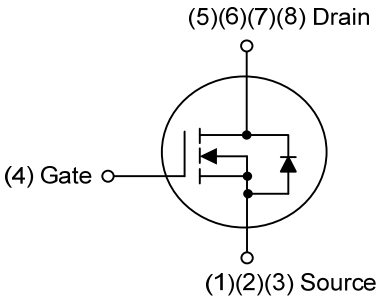
■ FEATURES

* $R_{DS(ON)} \leq 60\ m\Omega$ @ V_{GS} =10V, I_D =10A
  $R_{DS(ON)} \leq 75\ m\Omega$ @ V_{GS} =4.5V, I_D =10A
* Simple drive requirement

■ SYMBOL



TO-252

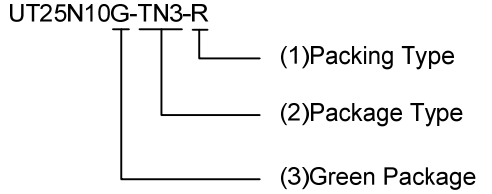


SOP-8 / PDFN3×3 / PDFN5×6

■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment								Packing
Lead Free	Halogen Free		1	2	3	4	5	6	7	8	
UT25N10L-TN3-R	UT25N10G-TN3-R	TO-252	G	D	S	-	-	-	-	-	Tape Reel
UT25N10L-S08-R	UT25N10G-S08-R	SOP-8	S	S	S	G	D	D	D	D	Tape Reel
UT25N10L-P3030-R	UT25N10G-P3030-R	PDFN3×3	S	S	S	G	D	D	D	D	Tape Reel
UT25N10L-P5060-R	UT25N10G-P5060-R	PDFN5×6	S	S	S	G	D	D	D	D	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

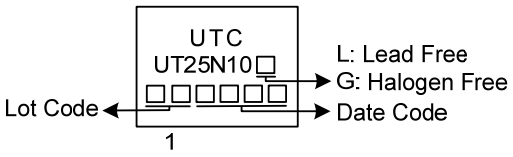
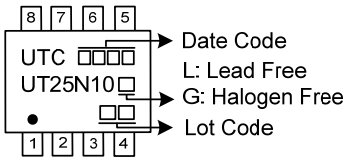
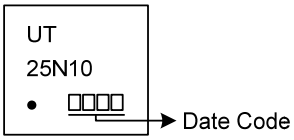
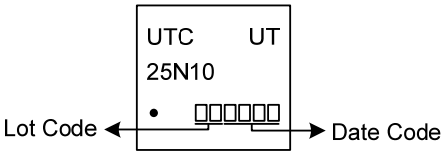


(1) R: Tape Reel

(2) TN3: TO-252, S08: SOP-8, P3030: PDFN3×3
P5060: PDFN5×6

(3) G: Halogen Free and Lead Free, L: Lead Free

■ MARKING

TO-252	SOP-8
	
PDFN3×3	**PDFN5×6**
	

■ ABSOLUTE MAXIMUM RATING (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	±20	V
Drain Current	Continuous	I_D	25	A
	Pulsed (Note 2)	I_{DM}	50	A
Power Dissipation	TO-252	P_D	44	W
	SOP-8		4.8	W
	PDFN3×3		20	W
	PDFN5×6		24	W
Junction Temperature		T_J	+150	°C
Storage Temperature Range		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-252	θ_{JA}	110	°C/W
	SOP-8		125	°C/W
	PDFN3×3		130	°C/W
	PDFN5×6		65	°C/W
Junction to Case	TO-252	θ_{JC}	2.85 (Note)	°C/W
	SOP-8		26 (Note)	°C/W
	PDFN3×3		6.25 (Note)	°C/W
	PDFN5×6		5.2 (Note)	°C/W

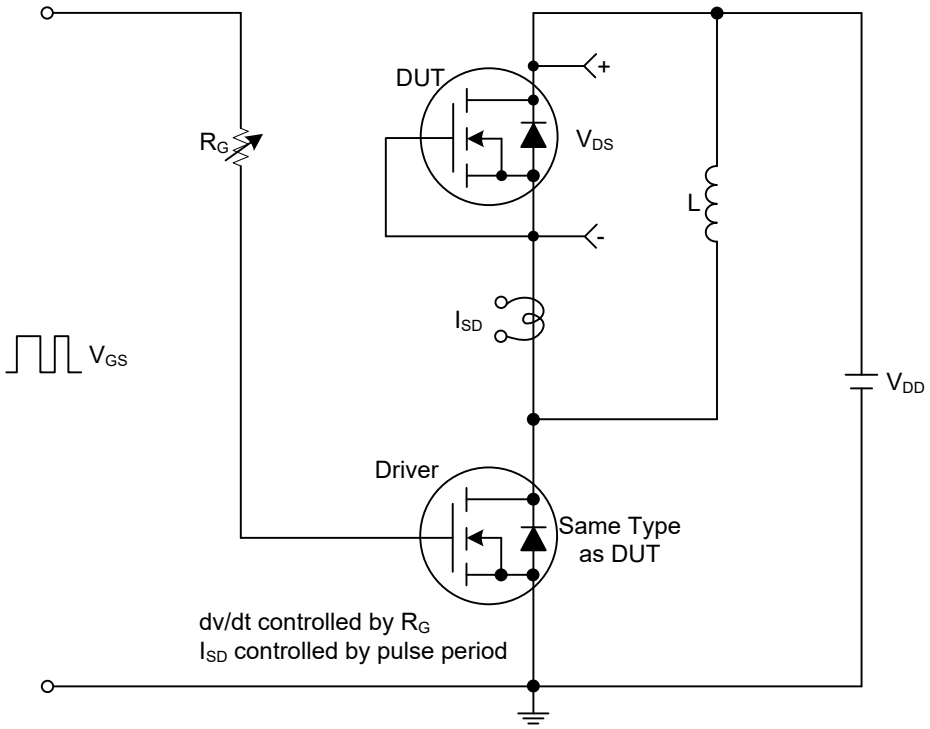
Note: Device mounted on FR-4 substrate P_C board, 2oz copper, with 1inch square copper plate.

■ ELECTRICAL CHARACTERISTICS (T_J =25°C, unless otherwise specified)

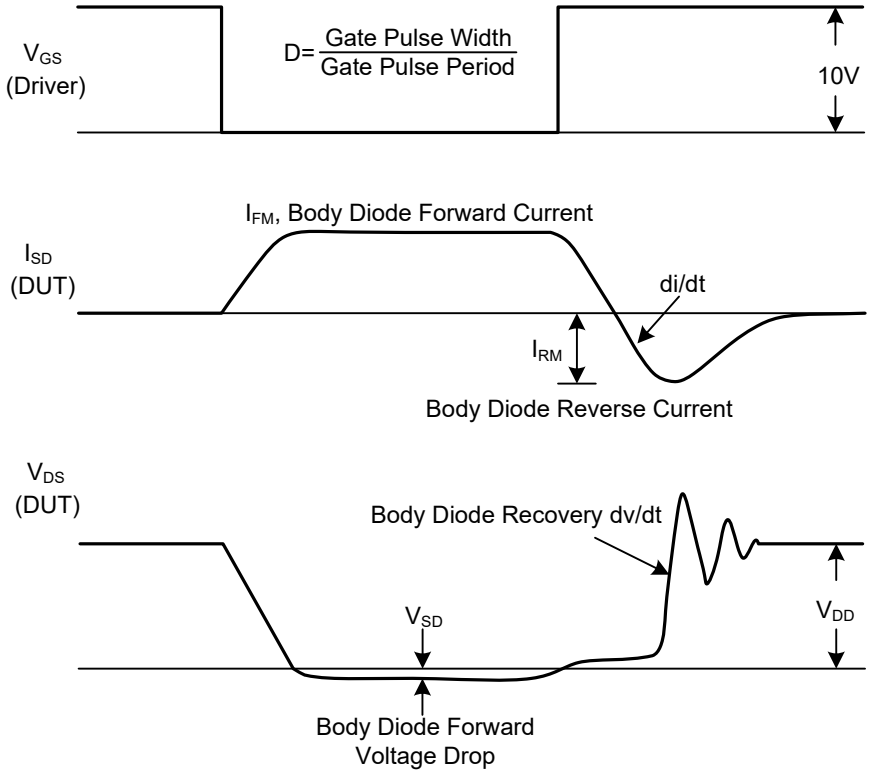
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} =0V, I_D =250μA	100			V
Drain-Source Leakage Current	I_{DSS}	V_{DS} =100V,V_{GS} =0V			1	μA
Gate-Source Leakage Current	I_{GSS}	V_{GS} =±20V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	V_{DS} =V_{GS}, I_D =250μA	1.0		3.0	V
Drain to Source On-state Resistance	$R_{DS(ON)}$	V_{GS} =10V, I_D =10A			60	mΩ
		V_{GS} =4.5V, I_D =10A			75	mΩ
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	V_{DS}=25V,V_{GS}=0V, f =1.0MHz		1550		pF
Output Capacitance	C_{OSS}			110		pF
Reverse Transfer Capacitance	C_{RSS}			90		pF
SWITCHING PARAMETERS						
Total Gate Charge (Note 1)	Q_G	V_{DS}=50V, V_{GS}=10V, I_D=25A (Note 1, 2)		50		nC
Gate Source Charge	Q_{GS}			8		nC
Gate Drain Charge	Q_{GD}			14		nC
Turn-ON Delay Time (Note 1)	$t_{D(ON)}$	V_{DD}=50V, V_{GS}=10V, I_D=25A, R_G =3Ω (Note 1, 2)		8		ns
Turn-ON Rise Time	t_R			16		ns
Turn-OFF Delay Time	$t_{D(OFF)}$			19		ns
Turn-OFF Fall-Time	t_F			18		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Continuous Drain-Source Diode Forward Current	I_S				25	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				50	A
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	I_S =25A, V_{GS} =0V			1.4	V
Reverse Recovery Time (Note 1)	t_{rr}	I_S=25A,V_{GS}=0V, dI/dt=100A/μs		106		ns
Reverse Recovery Charge	Q_{rr}			131		nC

Notes: 1. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS



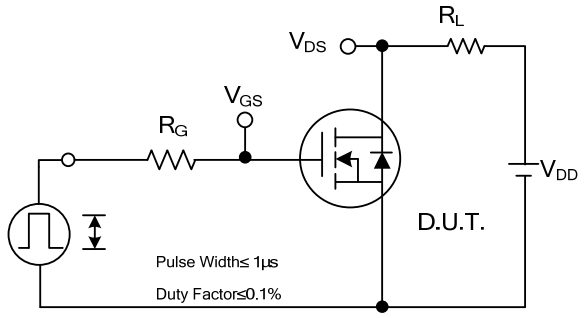
Peak Diode Recovery dv/dt Test Circuit



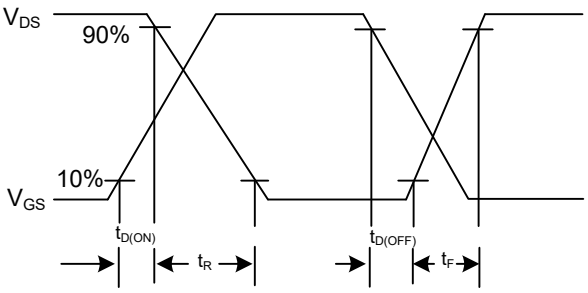
Peak Diode Recovery dv/dt Test Circuit and Waveforms

Peak Diode Recovery dv/dt Waveforms

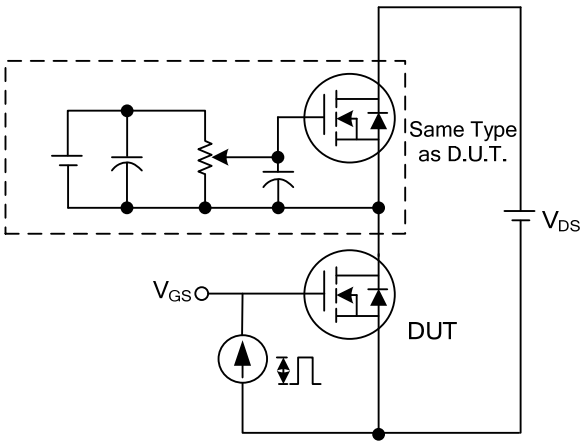
■ TEST CIRCUITS AND WAVEFORMS



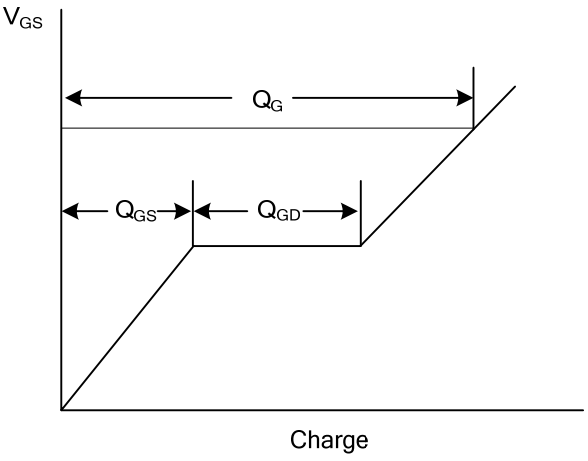
Switching Test Circuit



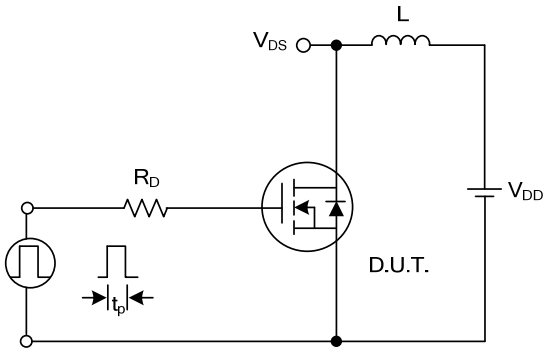
Switching Waveforms



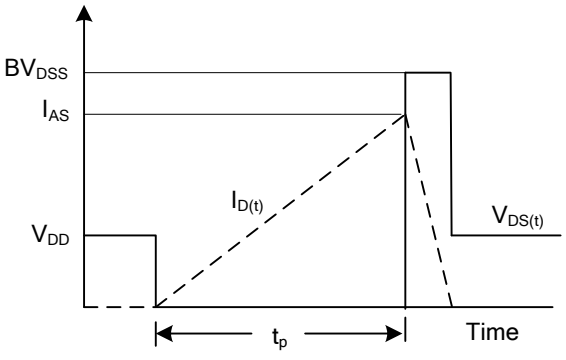
Gate Charge Test Circuit



Gate Charge Waveform



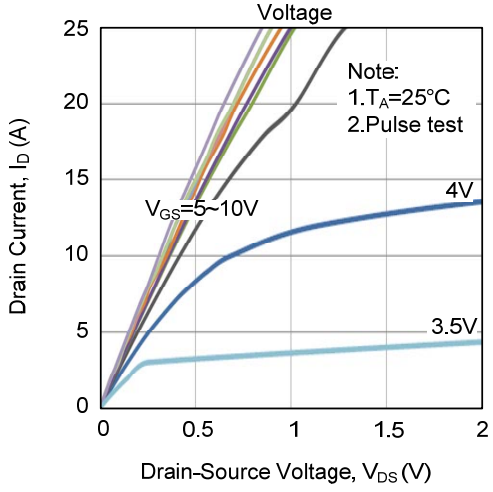
Unclamped Inductive Switching Test Circuit



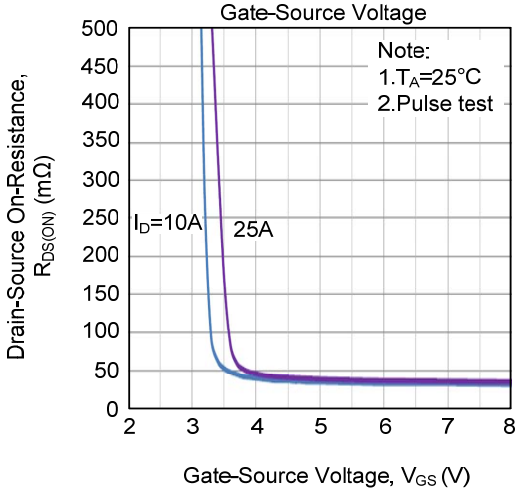
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

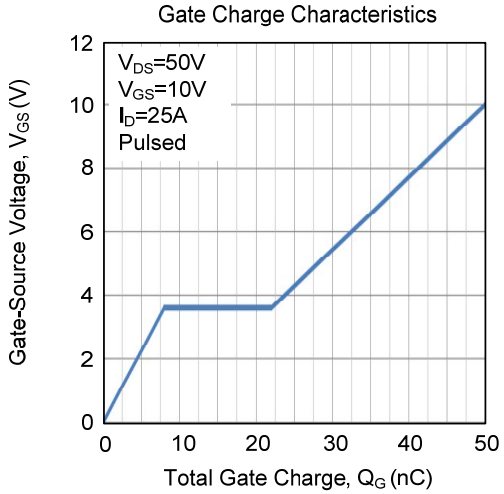
Drain Current vs. Drain-Source Voltage



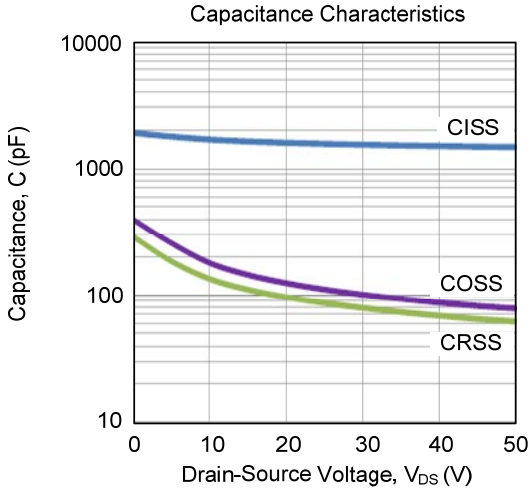
Drain-Source On-Resistance vs. Gate-Source Voltage



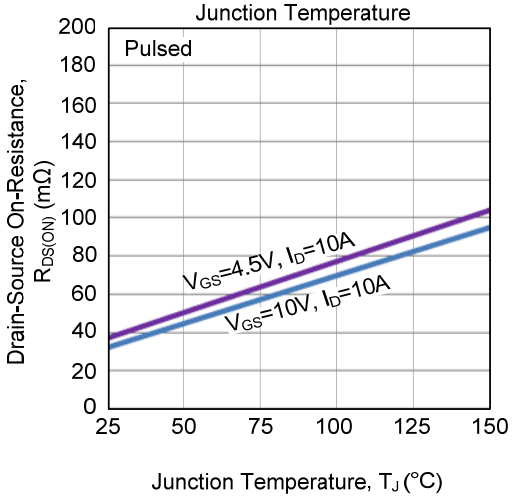
Gate Charge Characteristics



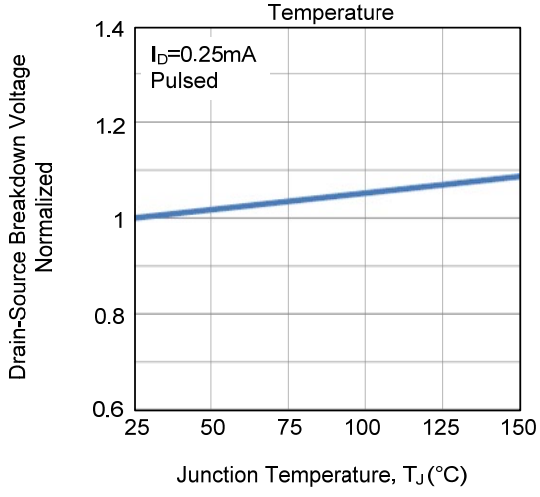
Capacitance Characteristics



Drain-Source On-Resistance vs. Junction Temperature

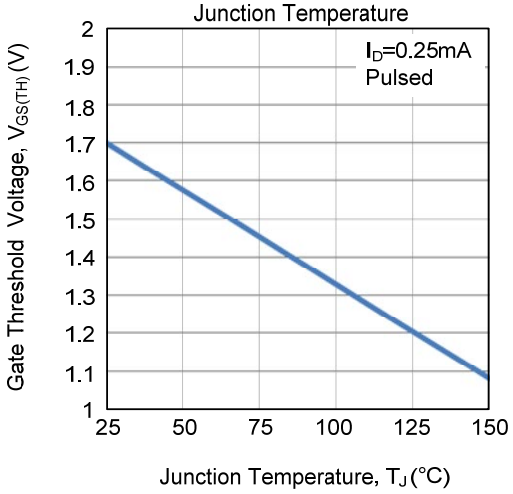


Breakdown Voltage vs. Junction Temperature

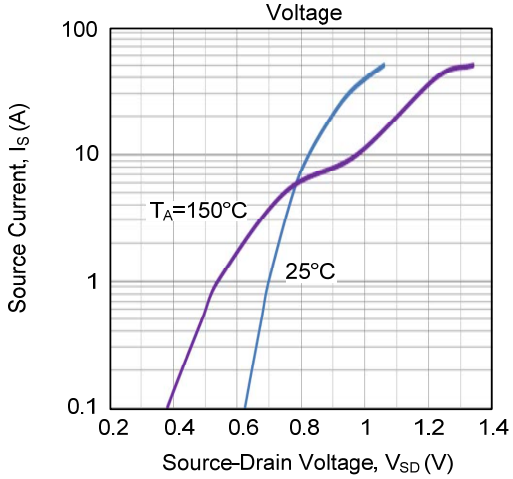


■ TYPICAL CHARACTERISTICS (Cont.)

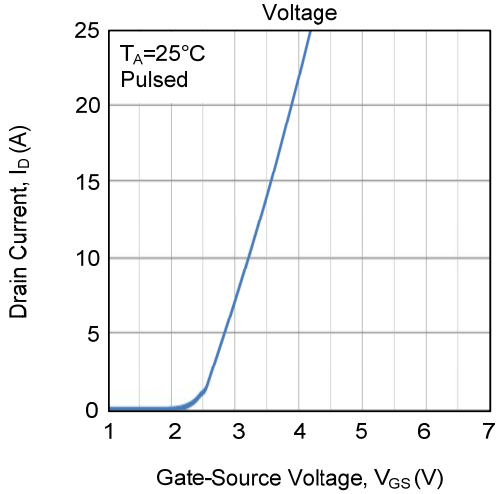
Gate Threshold Voltage vs. Junction Temperature



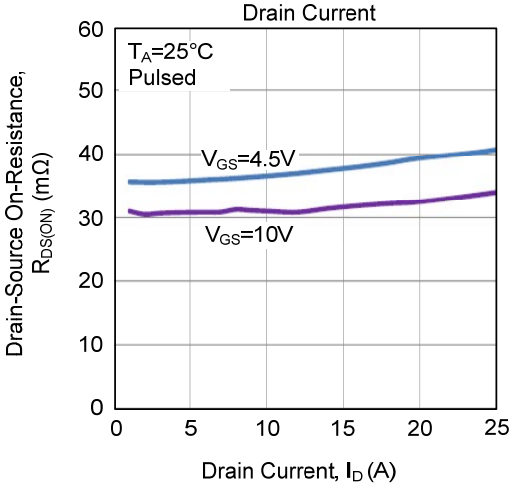
Source Current vs. Source-Drain Voltage



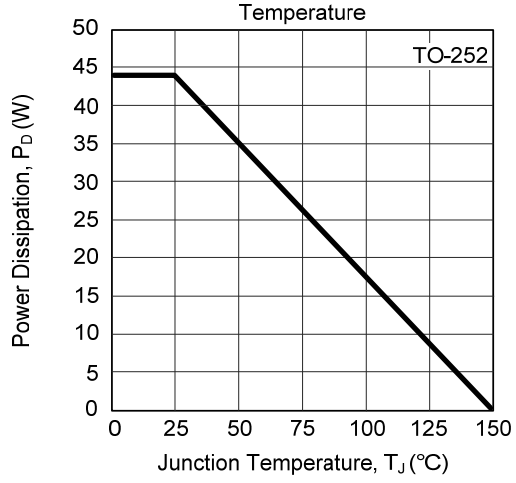
Drain Current vs. Gate-Source Voltage



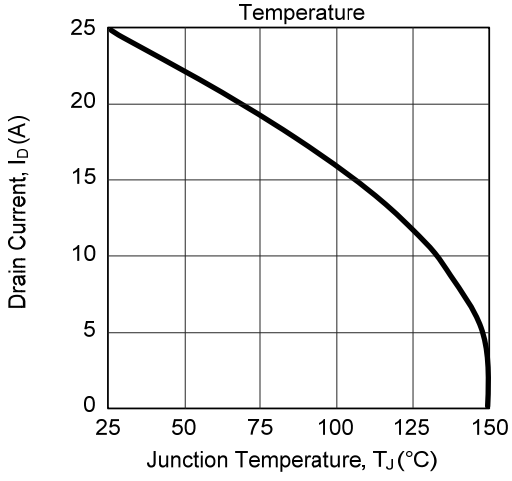
Drain-Source On-Resistance vs. Drain Current



Power Dissipation vs. Junction Temperature



Drain Current vs. Junction Temperature



■ TYPICAL CHARACTERISTICS (Cont.)